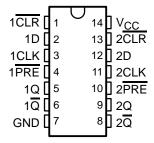
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- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- EPIC™ (Enhanced-Performance Implanted CMOS) Process
- Operating Range 2-V to 5.5-V V_{CC}
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

D OR PW PACKAGE (TOP VIEW)



description/ordering information

The SN74AHC74 dual positive-edge-triggered device is a D-type flip-flop.

A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

ORDERING INFORMATION

TA	PACKA	\GE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
55°C to 135°C	SOIC - D	Tape and reel	SN74AHC74MDREP	AHC74MEP	
–55°C to 125°C	TSSOP - PW	Tape and reel	SN74AHC74MPWREP	AHC74EP	

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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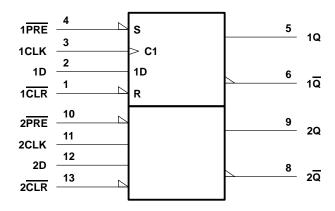
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FUNCTION TABLE (each flip-flop)

	INP	UTS		OUTI	PUTS
PRE	CLR	CLK	D	Q	Q
L	Н	Х	Х	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	H [†]	H [†]
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Χ	Q ₀	\overline{Q}_0

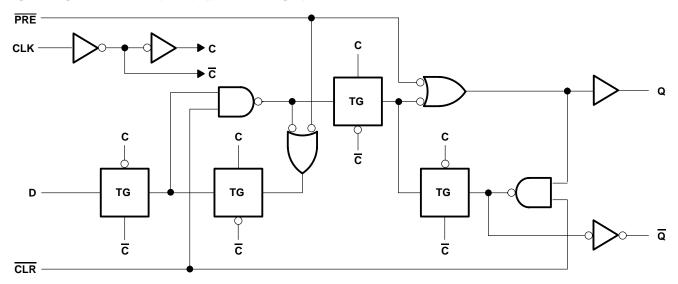
[†] This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

logic symbol‡



[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each flip-flop (positive logic)





SN74AHC74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Output voltage range, VO (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	–20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	V
		V _{CC} = 2 V	1.5		
٧ıH	High-level input voltage	V _{CC} = 3 V	2.1		V
		$V_{CC} = 5.5 V$	3.85		
		V _{CC} = 2 V		0.5	
V_{IL}	Low-level input voltage	$V_{CC} = 3 V$		0.9	V
		$V_{CC} = 5.5 \text{ V}$		1.65	
٧ _I	Input voltage		0	5.5	V
Vo	Output voltage		0	VCC	V
		V _{CC} = 2 V		-50	μΑ
ІОН	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	mA
		$V_{CC} = 5 V \pm 0.5 V$		-8	IIIA
		V _{CC} = 2 V		50	μΑ
loL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4	A
		$V_{CC} = 5 V \pm 0.5 V$		8	mA
A+/A>.	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$			100	ns/V
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		20	115/V
T _A	Operating free-air temperature		-55	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN74AHC74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	Vaa	T,	չ = 25°C	;	MINI	MAX	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	WAX	ONIT
		2 V	1.9	2		1.9		
Voн	I _{OH} = -50 μA	3 V	2.9	3		2.9		
		4.5 V	4.4	4.5		4.4		V
	I _{OH} = -4 mA	3 V	2.58			2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8		
		2 V			0.1		0.1	
	I _{OL} = 50 μA	3 V			0.1		0.1	
V _{OL}		4.5 V			0.1		0.1	V
	$I_{OL} = 4 \text{ mA}$	3 V			0.36		0.5	
	$I_{OL} = 8 \text{ mA}$	4.5 V			0.36		0.5	
lį	$V_I = 5.5 \text{ V or GND}$	0 V to 5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	μΑ
Ci	V _I = V _{CC} or GND	5 V		2	10			pF

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	MIN	MAX	UNIT	
			MIN	MAX	IVIIIN	WAA	UNIT	
	Pulse duration	PRE or CLR low	6		7		no	
t _W	ruise duration	CLK	6		7		ns	
Γ.	Octors that a harfage OLIVA	Data	6		7			
t _{su}	Setup time before CLK↑	PRE or CLR inactive	5		5		ns	
th	Hold time, data after CLK↑	0.5		0.5		ns		

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A = 25°C		MIN	MAX	UNIT
		MIN	MAX] WIIIN	WAX	UNII	
t _W	Pulse duration	PRE or CLR low	5		5		
	Fulse duration	CLK	5		5		ns
	Octor Core haters OLKA	Data	5		5		
t _{su}	Setup time before CLK↑	PRE or CLR inactive	3		3		ns
t _h	Hold time, data after CLK↑	_	0.5		0.5		ns

SN74AHC74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	Վ = 25° C	;	MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIN	IVIAA	UNIT
f _{max}			C _L = 15 pF	80	125		70		MHz
			C _L = 50 pF	50	75		45		IVITZ
tPLH	<u> </u>	0	C _I = 15 pF		7.6	12.3	1	14.5	ns
t _{PHL}	PRE or CLR	Q or Q	OL = 13 pi		7.6	12.3	1	14.5	1115
tPLH	CLK	0	C: - 15 pE		6.7	11.9	1	14	ns
t _{PHL}	CLK	Q or Q	C _L = 15 pF		6.7	11.9	1	14	115
tPLH	DDE OLD	0	C 50 pE		10.1	15.8	1	18	ns
t _{PHL}	PRE or CLR	Q or $\overline{\mathbb{Q}}$	$C_L = 50 \text{ pF}$		10.1	15.8	1	18	115
t _{PLH}	CLK	Q or $\overline{\mathbb{Q}}$	C: - 50 pF		9.2	15.4	1	17.5	no
t _{PHL}	CLK	Q OF Q	C _L = 50 pF		9.2	15.4	1	17.5	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	գ = 25°C	;	MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIV	IVIAA	UNII
			C _L = 15 pF	130	170		110		MHz
f _{max}			C _L = 50 pF	90	115		75		IVITIZ
t _{PLH}	DDE OLD	0	C _L = 15 pF		4.8	7.7	1	9	ns
t _{PHL}	PRE or CLR	Q or Q	OL = 13 pi		4.8	7.7	1	9	110
^t PLH	CLK	Q or $\overline{\mathbb{Q}}$	C _L = 15 pF		4.6	7.3	1	8.5	ns
t _{PHL}	CLK	Q or Q			4.6	7.3	1	8.5	113
^t PLH	PRE or CLR	Q or Q	C _L = 50 pF		6.3	9.7	1	11	ns
^t PHL	PRE OF CLR	Q or Q	CL = 30 pr		6.3	9.7	1	11	115
^t PLH	CLK	Q or Q	C _L = 50 pF		6.1	9.3	1	10.5	ns
^t PHL	CLK	3013	CL = 50 pr		6.1	9.3	1	10.5	110

noise characteristics, $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 4)

	PARAMETER	MIN	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}	4.7		V
V _{IH(D)}	High-level dynamic input voltage	3.5		V
V _{IL(D)}	Low-level dynamic input voltage		1.5	V

NOTE 4: Characteristics are for surface-mount packages only.

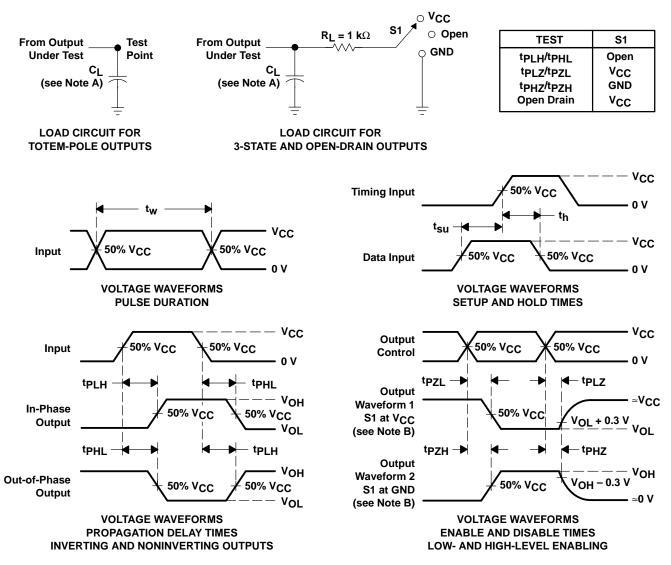
operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Γ	Power dissipation capacitance	No load, f = 1 MHz	32	pF



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns. $t_f \leq 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHC74MDREP	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC74MEP	Samples
V62/03652-01YE	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHC74MEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN74AHC74-EP:

Catalog : SN74AHC74

• Military : SN54AHC74

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	-
A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC74MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHC74MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC74MDREP	SOIC	D	14	2500	340.5	336.1	32.0
SN74AHC74MPWREP	TSSOP	PW	14	2000	356.0	356.0	35.0

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